

300
mm

FOUP



KT-3003

■ 观念

- 根据SEMI规格(E1.9/E47.1/E15.1/E57/E62)
 - 主要零件全部使用电导化材料
 - 为了考虑环境, 产品的设计是只要换所需要的部件就可以, 这样在省资源, 再利用时可以分类
-
- SEMI Standard compliant (E1.9/E47.1/E15.1/E57/E62)
 - All major components manufactured from conductive materials
 - In consideration of environment, design enabling only the necessary parts to be replaced makes it possible to separate resources when recycling



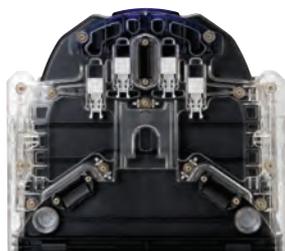
Front



Top



Rear



Bottom

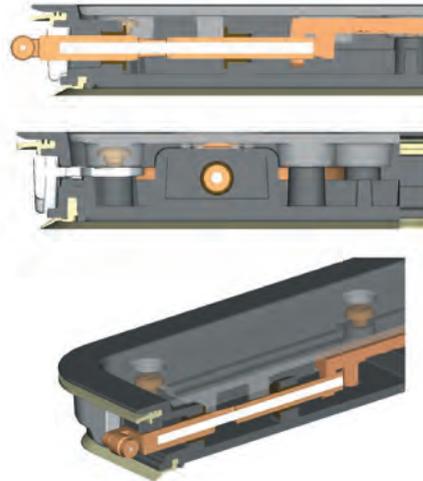


Feature A

关于微粒 (particle) Particle Related

- 在盖子的侧面以及内面采用了两个Gasket零部件
盖子和本体之间的隔绝是两层化, 这样可以防止从外部进入的微粒 (particle)
- 在盖子内部采用了"圆型的门锁 (latch)" 这样会使门锁键周边的开口面积变得极小 (只有轴和轴承的空间), 并防止从盖子内部的飞散

- Two gaskets are adopted on the cover side and inner surface
Dual isolation of the cover and shell prevents invasion by foreign particles.
- Minimizing the opening area (to just the clearance between shaft and bearing) around the latchkey by adopting a "round pushrod" inside the cover prevents particle migration from inside the cover



Feature B

关于搬运 Enhanced Shell Integrity

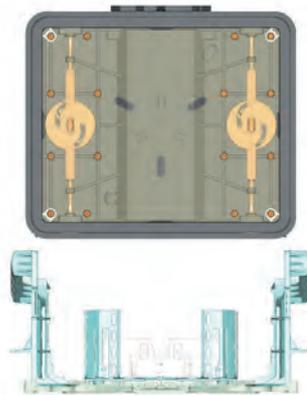
- 本体和Top Flange部的装设部分的加强 (给本体上面追加rib) 及在开口部的Flange部本来是一到二条的rib改变成3条

- Top flange of the shell has been reinforced (with additional rib), and flange ribs at the opening have been increased from 1 or 2 to 3



- 把Bottom/Side的Conveyor rail装设部从本体切离这样会防止密封性降低

- Bottom/side conveyor rail assembly is separate from the shell to prevent deterioration of seal performance caused by shell deformation



Feature C

- 晶片的收容量用26片 (第26片是假的晶片,这是因为保护邻接本体内部的最上面的晶片)
- 在后面装备了RFID Holder
被后部方面装备RF ID持有人
- SIDE HANDLE, OUT SIDE LID, 可以上颜色 (关于颜色的询问请联系各营业负责人)
- 本体清洗性: 采用了在清洗时,可以容易清洗,并且容易干的结构
- 盖子上下防止误插入机构: 本体和盖子指南开关的上下防止误插入机构
- 视认性: 从本体底部看时,可以视认晶片
- 晶片在移载时的摩擦: 晶片移载起重机时与沟盖板等不会有摩擦的形状
- 抵抗温度(材料性质): 沟盖板部上使用PEEK
- 带电特性: 本体, 沟盖板, 盖子的ESD材的特性为表面抵抗值程度是E7到10

- Wafer capacity increased to 26 wafers (26th wafer is a dummy wafer offering protection from the inner face of the shell to the top wafer surface)
- RF ID tag is available (holder on the rear side)
- Side handles and outside lid are available in colors
- Shell washability: Shell structure is designed to enable easy washing and drying
- Anti-inversion cover offers protection against wrong insertion when manually opening and closing the shell and cover
- Visibility: Wafers are clearly visible from the shell rear
- Wafer pocket design prevents friction during handling
- PEEK is used for wafer supports for high temperature resistance
- Surface resistivity of the shell: wafer supports and cover $10^7 \sim 10^{10} \Omega/\text{cm}^2$

